Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

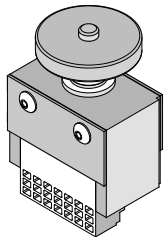
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

HS Dock™ Wafer Extraction Tool

molex

Application Tooling Specification Sheet



Order No. 62202-3400

FEATURES

- This tool is designed for the removal of the wafer sub-assembly from a Right Angle HS Dock™ Receptacle connector assembly. (To remove wafers from a plug assembly, use tool 62202-0220, 62202-0260, 62202-0280, or 62202-0290.)
- This tool can be used on any circuit size receptacle after the upper housing is removed. Refer to 62202-3200 (144 Circuit) or 62202-3300 (108 Circuit) for upper housing removal.
- After the Wafer Sub-Assemblies are removed the Lower Housing can be removed from the PCB.

SCOPE

Products: 1.20mm by 3.50mm Pitch HS Dock+ and Plateau HS Dock™ Receptacle, Right Angle, 72 to 144 Circuits. See Product List below for specific part numbers.

Product List

The following is a partial list of the product order numbers and their specifications this tool is designed to run. Updates to this list are available on www.molex.com.

Series No.	Circuit Size	Assembly Order Number							
75019	72	75019-0100	75019-0301	75019-0305	75019-2004	75019-7100			
	108	75019-0013	75019-0017	75019-0019	75019-0021	75019-0302	75019-0304	75019-2003	75019-2005
		75019-2006	75019-7013	75019-7017	75019-7021	75019-7113	75019-7213	75019-7217	75019-7221
		75019-7313	75019-7317						
	120	75019-0014	75019-7214	75019-7314					
	144	75019-0015	75019-0016	75019-0017	75019-0018	75019-0306	75019-2001	75019-2007	75019-7024
		75019-7215	75019-7216	75019-7315	75019-7316				
74149	108	74149-1002	74149-1102	74149-2002	74149-3002	74149-3102	74149-4002	74149-4102	74149-5002
		74149-5102							
	144	74149-1001	74149-1101	74149-2001	74149-3001	74149-3101			

Tool Setup

1. Remove the upper housing using tool 62202-3200 or 62202-3300.
2. Before removing the wafer sub-assemblies the retainer clip must be removed. See Figure 1. To do this, firmly grip the top of the retainer clip and rock it back and forth until it pulls free from the lower housing.

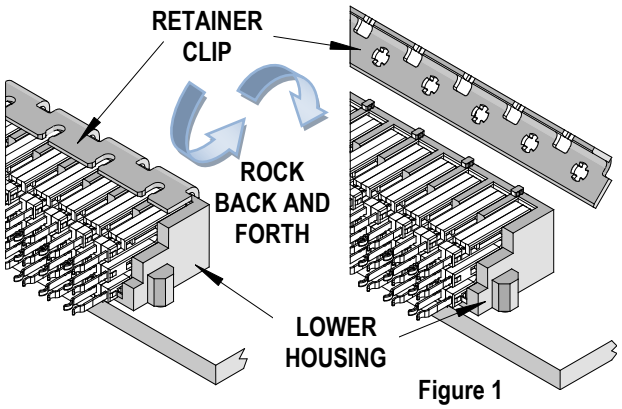


Figure 1

Tool Operation

To use the Wafer Removal Tool follow the steps below:

1. Before using this tool make sure it is in its original position. Rotate the knob on the top of the Wafer Removal Tool counter counterclockwise (CCW) until it stops.
2. Place Wafer Removal Tool with the slots over the contacts of the wafers as shown. The wafer contacts should be visible thru the slots of the tool block. See Figure 2.
3. Turn the knob clockwise (CW) to pull up the wafers until they are removed from printed circuit board. See Figure 3.
4. Move the tool to the next group of seven wafers and repeat step 1-4 until all wafers have been removed.

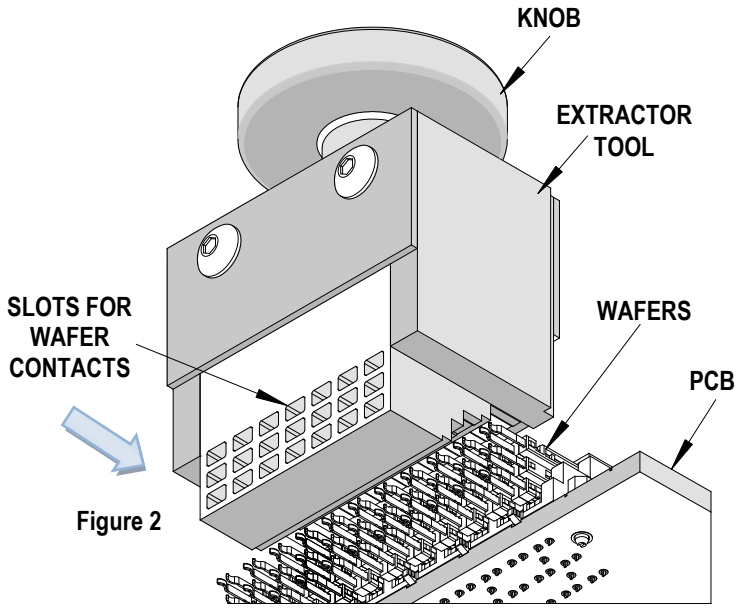


Figure 2

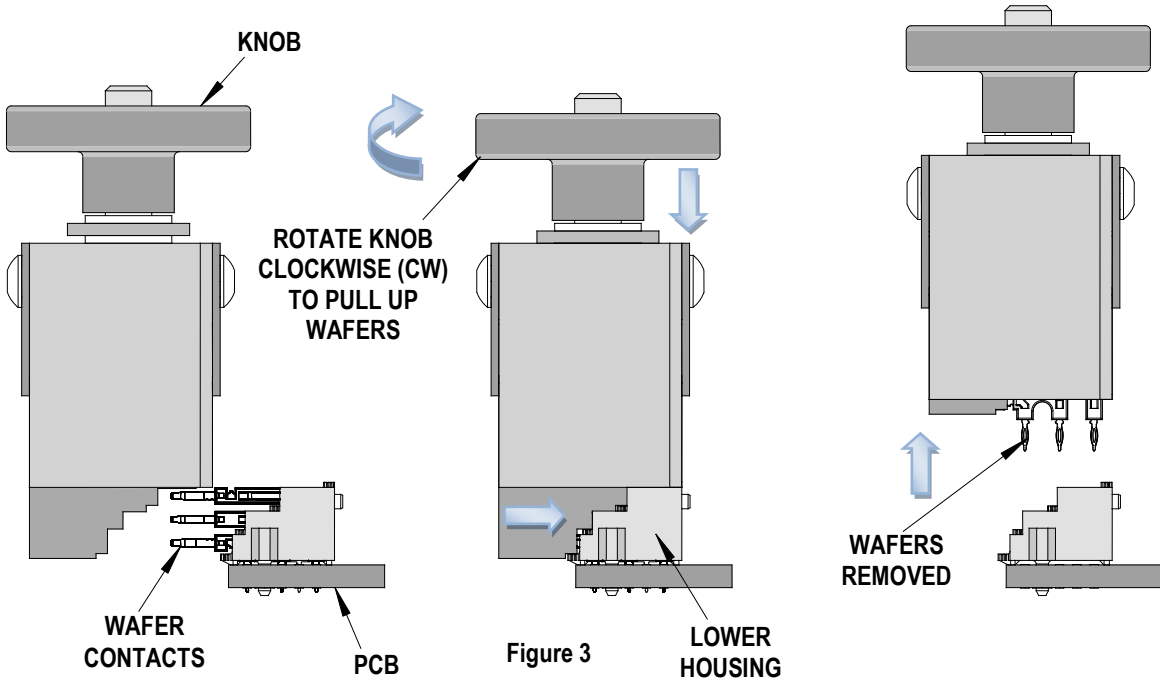


Figure 3

Note: When removing end wafers, make sure the Wafer Removal Tool is aligned with the last wafer contact in the lower housing. See Figure 2

5. Next remove the lower housing from printed circuit board by using a Needle Nose Pliers. Pull up on the side wall of the housing until it is out of the printed circuit board. Then do the same to the opposite end until it disengages from the printed circuit board. Set aside. See Figure 4.

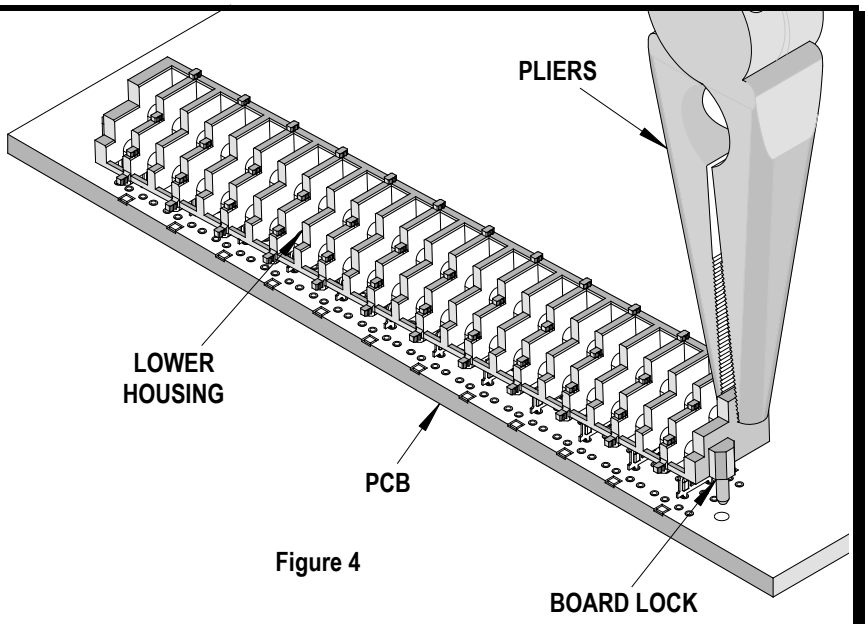


Figure 4

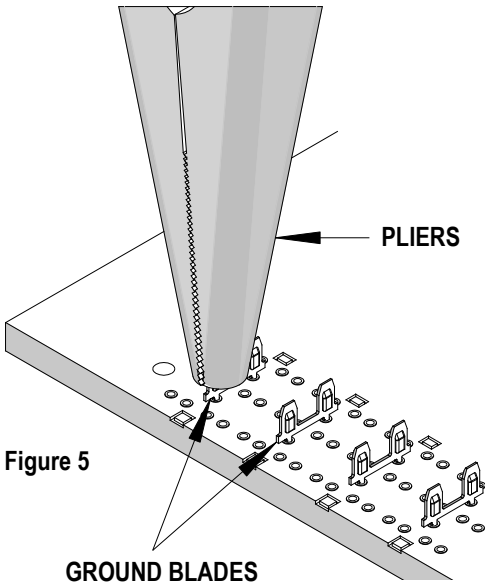


Figure 5

6. Remove the remaining ground blades from the printed circuit board using Needle Nose Pliers. See Figure 5.

CAUTION: Molex application tooling specifications are valid only when used with Molex connectors and tooling.

Contact Information

For more information on Molex application tooling please contact Molex at 1-800-786-6539.

Visit our Web site at http://www.molex.com